

## C1210X223G2TACTU

Aliases (C1210X223G2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.022 uF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information			
Series	SMD Comm X8G HT150C Flex		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No		
AEC-Q200	No		
Typical Component Weight	40 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions		
Chip Size	1210	
L	3.3mm +/-0.4mm	
W	2.6mm +/-0.3mm	
Т	1.1mm +/-0.15mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

1	1.lmm +/-0.15mm		
S	1.5mm MIN		
В	0.6mm +/-0.25mm		
Packaging Specifications			
Packaging	T&R, 180mm, Plastic Tape		

2500

Packaging Quantity

Specifications			
Capacitance	0.022 uF		
Measurement Condition	1 kHz 1.0Vrms		
Tolerance	2%		
Voltage DC	200 VDC		
Dielectric Withstanding Voltage	500 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	45.4545 GOhms		

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